J&R Mechanical and Tea Weekly



2025 ETHAN DAVID CHAPMAN SCHOLARSHIP APPLICATION

The "Ethan David Chapman Scholarship" is open to TEA AREA SENIORS enrolled for Fall Semester 2025 in any two- or four-year post-secondary school, regardless of major or GPA. Applications are due May 5, 2025.

Scholarship amount: \$1000, payable to student upon proof of enrollment.

Return to: Tea Weekly, Po Box 98, Tea, SD 57064

APPLICANT INFORMATION:

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hone Number:	Email address:	
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Name of Organization	Position	Dates Active
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Name of Organization	Job title or role	Dates Employed
Post-Secondary School	Field of Study	
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we mean brief, think Twitter Siz	ed. There's plenty of other essays to wr	rite — this is not an essay.